Dual 12-Bit *nano*DAC with ±10 ppm/°C On-Chip Reference

Data Sheet

AD5623R-EP

FEATURES

Enhanced product features
Military temperature range: −55°C to +105°C
Low power, smallest pin-compatible, dual *nano*DAC: 12 bits
User-selectable external or internal reference
External reference default
On-chip 2.5 V, ±10 ppm/°C reference
10-lead MSOP
4.5 V to 5.5 V power supply
Guaranteed monotonic by design
Power-on reset to zero scale
Per channel power-down
Serial interface up to 50 MHz
Hardware $\overline{\text{LDAC}}$ and $\overline{\text{CLR}}$ functions

APPLICATIONS

Process control
Data acquisition systems

GENERAL DESCRIPTION

The AD5623R-EP, a member of the *nano*DAC® family, is a low power, dual 12-bit buffered voltage output digital-to-analog converter (DAC) that operates from a single 4.5 V to 5.5 V supply and is guaranteed monotonic by design.

The AD5623R-EP has an on-chip 2.5 V reference giving a maximum full-scale output of 5 V. The on-chip reference is off at power-up, allowing the use of an external reference.

The AD5623R-EP incorporates a power-on reset circuit that ensures that the output of the DACs powers up to 0 V and remains there until a valid write takes place. The AD5623R-EP contains a power-down feature that reduces the current consumption of the device to 0.48 µA at 5 V and provides software-selectable output loads while in power-down mode.

The low power consumption of this device in normal operation makes it ideally suited to portable, battery-operated equipment.

The AD5623R-EP uses a versatile, 3-wire serial interface that operates at clock rates of up to 50 MHz, and is compatible with standard SPI, QSPI™, MICROWIRE™, and DSP interface standards. The on-chip precision output amplifier enables rail-to-rail output swing to be achieved. Additional application and technical information can be found in the AD5623R data sheet.

PRODUCT HIGHLIGHTS

1. Dual 12-Bit DAC.
2. On-Chip 2.5 V, ±10 ppm/°C Reference.
3. Available in 10-Lead MSOP.
4. Low Power. Typically consumes 1.25 mW at 5 V. 4.5 µs maximum settling time.

Table 1. Related Device

Part No.	Description
AD5623R	2.7 V to 5.5 V, dual 12-bit *nano*DAC, with external reference

FUNCTIONAL BLOCK DIAGRAM

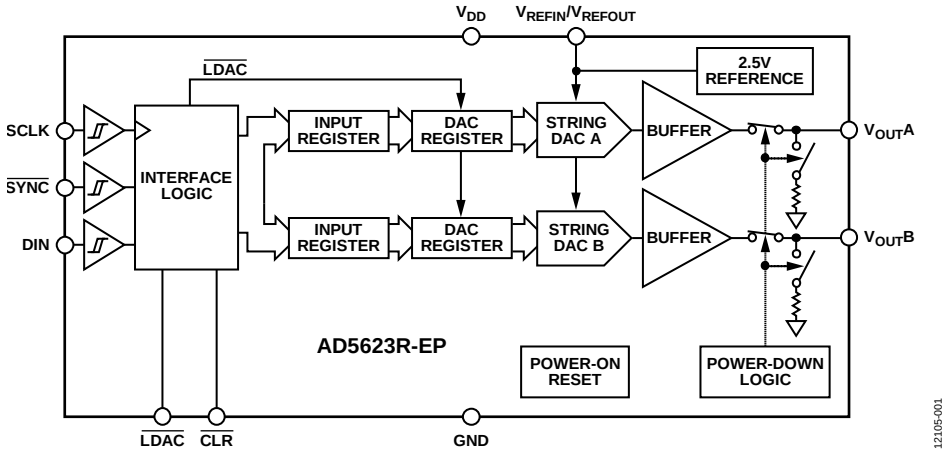

Figure 1.

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Technical Support www.analog.com

TABLE OF CONTENTS

REVISION HISTORY

2/14—Revision 0: Initial Version

SPECIFICATIONS

V_{DD} = 4.5 V to 5.5 V; R_L = 2 kΩ to GND; C_L = 200 pF to GND; $V_{REFIN}/V_{REFOUT} = V_{DD}$; all specifications T_{MIN} to T_{MAX}, unless otherwise noted.

Table 2.

Parameter[1]	Min	Typ	Max	Unit	Test Conditions/Comments
STATIC PERFORMANCE[2, 3]					
Resolution	12			Bits	
Relative Accuracy, INL		±1	±1.5	LSB	
Differential Nonlinearity, DNL			±1	LSB	Guaranteed monotonic by design
Zero-Scale Error		+2	+12	mV	All 0s loaded to DAC register
Offset Error		±1	±12	mV	
Full-Scale Error		−0.1	±1	% of FSR	All 1s loaded to DAC register
Gain Error			±1.5	% of FSR	
Zero-Scale Error Drift		±2		µV/°C	
Gain Temperature Coefficient		±2.5		ppm	Of FSR/°C
DC Power Supply Rejection Ratio		−100		dB	DAC code = midscale; V_{DD} = 5 V ± 10%
DC Crosstalk					
External Reference		10		µV	Due to full-scale output change; R_L = 2 kΩ to GND or V_{DD}
		10		µV/mA	Due to load current change
		5		µV	Due to powering down (per channel)
Internal Reference		25		µV	Due to full-scale output change; R_L = 2 kΩ to GND or V_{DD}
		20		µV/mA	Due to load current change
		10		µV	Due to powering down (per channel)
OUTPUT CHARACTERISTICS[4]					
Output Voltage Range	0		V_{DD}	V	
Capacitive Load Stability		2		nF	$R_L = \infty$
		10		nF	R_L = 2 kΩ
DC Output Impedance		0.5		Ω	
Short-Circuit Current		30		mA	V_{DD} = 5 V
Power-Up Time		4		µs	Coming out of power-down mode; V_{DD} = 5 V
REFERENCE INPUTS					
Reference Current		170	200	µA	$V_{REFIN}/V_{REFOUT} = V_{DD}$ = 5.5 V
Reference Input Range	0.75		V_{DD}	V	
Reference Input Impedance		26		kΩ	
REFERENCE OUTPUT					
Output Voltage	2.495		2.505	V	At ambient
Reference Temperature Coefficient[4]		±10		ppm/°C	
Output Impedance		7.5		kΩ	
LOGIC INPUTS[4]					
Input Current			±2	µA	All digital inputs
Input Low Voltage (V_{INL})			0.8	V	V_{DD} = 5 V
Input High Voltage (V_{INH})	2			V	V_{DD} = 5 V
Pin Capacitance		3		pF	DIN, SCLK, and $\overline{SYNC}$
		19		pF	$\overline{LDAC}$ and $\overline{CLR}$
POWER REQUIREMENTS					
V_{DD}	4.5		5.5	V	
I_{DD} (Normal Mode)[5]					$V_{INH} = V_{DD}$ and V_{INL} = GND
Internal Reference Off		0.25	0.45	mA	V_{DD} = 4.5 V to 5.5 V
Internal Reference On		0.8	1	mA	V_{DD} = 4.5 V to 5.5 V
I_{DD} (All Power-Down Modes)[6]		0.48	1	µA	V_{DD} = 4.5 V to 5.5 V, $V_{INH} = V_{DD}$ and V_{INL} = GND

[1] Temperature range = −55°C to +105°C, typical at +25°C.
[2] Linearity calculated using a reduced code range: Code 32 to Code 4064. Output unloaded.
[3] See the Terminology section.
[4] Guaranteed by design and characterization, but not production tested.
[5] Interface inactive. All DACs active. DAC outputs unloaded.
[6] Both DACs powered down.

AC CHARACTERISTICS

V_{DD} = 4.5 V to 5.5 V; R_L = 2 kΩ to GND; C_L = 200 pF to GND; $V_{REFIN}/V_{REFOUT} = V_{DD}$; all specifications T_{MIN} to T_{MAX}, unless otherwise noted.

Table 3.

Parameter[1, 2, 3]	Min	Typ	Max	Unit	Test Conditions/Comments
SLEW RATE		1.8		V/µs	
FEEDTHROUGH					
Digital Feedthrough		0.1		nV-sec	
Reference Feedthrough		−90		dB	V_{REFIN}/V_{REFOUT} = 2 V ± 0.1 V p-p, frequency 10 Hz to 20 MHz
CROSSTALK					
Digital Crosstalk		0.1		nV-sec	
Analog Crosstalk		1		nV-sec	External reference
		4		nV-sec	Internal reference
DAC-to-DAC Crosstalk		1		nV-sec	External reference
		4		nV-sec	Internal reference
MULTIPLYING BANDWIDTH		340		kHz	V_{REFIN}/V_{REFOUT} = 2 V ± 0.1 V p-p
TOTAL HARMONIC DISTORTION		−80		dB	V_{REFIN}/V_{REFOUT} = 2 V ± 0.1 V p-p, frequency = 10 kHz
OUTPUT CHARACTERISTICS					
Digital-to-Analog Glitch Impulse		10		nV-sec	1 LSB change around major carry
Output Voltage Settling Time		3	4.5	µs	¼ to ¾ scale settling to ±0.5 LSB
Output Noise Spectral Density		120		nV/√Hz	DAC code = midscale, 1 kHz
		100		nV/√Hz	DAC code = midscale, 10 kHz
Output Noise		15		µV p-p	0.1 Hz to 10 Hz

[1] Guaranteed by design and characterization, but not production tested.
[2] See the Terminology section.
[3] Temperature range = −55°C to +105°C, typical at +25°C.

TIMING CHARACTERISTICS

All input signals are specified with $t_R = t_F$ = 1 ns/V (10% to 90% of V_{DD}) and timed from a voltage level of $(V_{INL} + V_{INH})/2$.
V_{DD} = 4.5 V to 5.5 V; all specifications T_{MIN} to T_{MAX}, unless otherwise noted.

Table 4.

Parameter[1]	Limit at T_{MIN}, T_{MAX}	Unit	Description
t_1[2]	20	ns min	SCLK cycle time
t_2	9	ns min	SCLK high time
t_3	9	ns min	SCLK low time
t_4	13	ns min	$\overline{SYNC}$ to SCLK falling edge setup time
t_5	5	ns min	Data setup time
t_6	5	ns min	Data hold time
t_7	0	ns min	SCLK falling edge to $\overline{SYNC}$ rising edge
t_8	15	ns min	Minimum $\overline{SYNC}$ high time
t_9	13	ns min	$\overline{SYNC}$ rising edge to SCLK fall ignore
t_{10}	0	ns min	SCLK falling edge to $\overline{SYNC}$ fall ignore
t_{11}	10	ns min	$\overline{LDAC}$ pulse width low
t_{12}	15	ns min	SCLK falling edge to $\overline{LDAC}$ rising edge
t_{13}	5	ns min	$\overline{CLR}$ pulse width low
t_{14}	0	ns min	SCLK falling edge to $\overline{LDAC}$ falling edge
t_{15}	300	ns max	$\overline{CLR}$ pulse activation time

[1] Guaranteed by design and characterization, but not production tested.
[2] Maximum SCLK frequency is 50 MHz at V_{DD} = 2.7 V to 5.5 V.

Timing Diagram

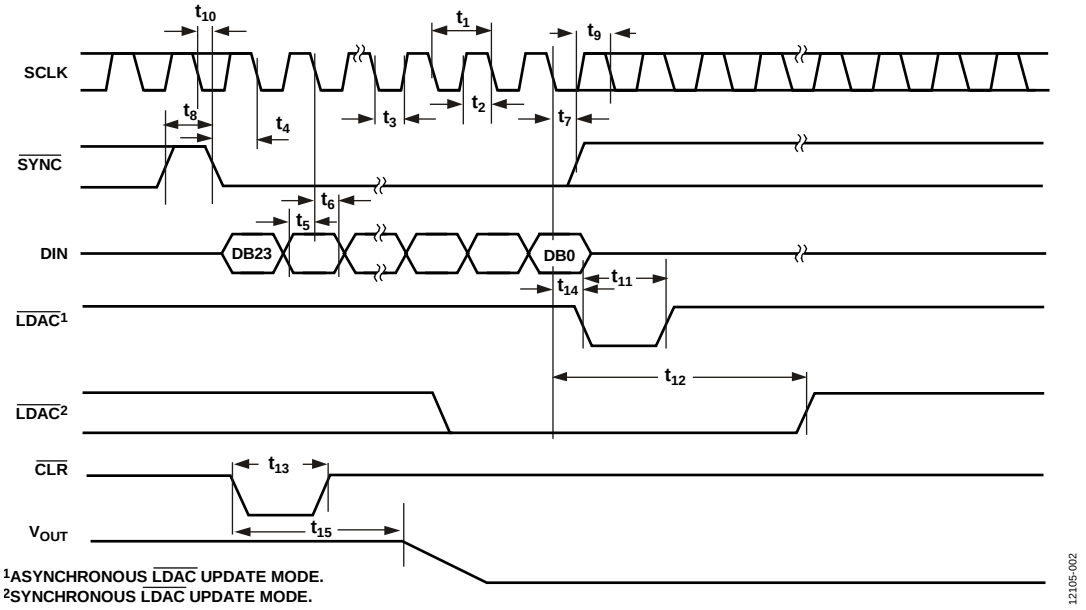

Figure 2. Serial Write Operation

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise noted.

Table 5.

Parameter	Rating
V_{DD} to GND	−0.3 V to +7 V
V_{OUTx} to GND	−0.3 V to V_{DD} + 0.3 V
V_{REFIN}/V_{REFOUT} to GND	−0.3 V to V_{DD} + 0.3 V
Digital Input Voltage to GND	−0.3 V to V_{DD} + 0.3 V
Operating Temperature Range	
Industrial	−40°C to +105°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature (T_J max)	150°C
Power Dissipation	(T_J max − T_A)/θ_{JA}
MSOP Package (4-Layer Board)	
θ_{JA} Thermal Impedance	142°C/W
θ_{JC} Thermal Impedance	43.7°C/W
Reflow Soldering Peak Temperature	
Pb-Free	260 (+0/−5)°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

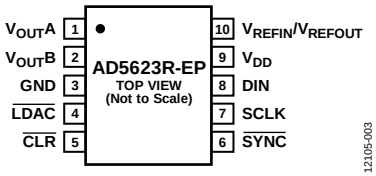

Figure 3. Pin Configuration

Table 6. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	$V_{OUT}A$	Analog Output Voltage from DAC A. The output amplifier has rail-to-rail operation.
2	$V_{OUT}B$	Analog Output Voltage from DAC B. The output amplifier has rail-to-rail operation.
3	GND	Ground. Reference point for all circuitry on the device.
4	$\overline{LDAC}$	Load DAC. Pulsing this pin low allows any or all DAC registers to be updated if the input registers have new data. This allows simultaneous update of all DAC outputs. Alternatively, this pin can be tied permanently low.
5	$\overline{CLR}$	Asynchronous Clear Input. The $\overline{CLR}$ input is falling edge sensitive. While $\overline{CLR}$ is low, all $\overline{LDAC}$ pulses are ignored. When $\overline{CLR}$ is activated, zero scale is loaded to all input and DAC registers. This clears the output to 0 V. The device exits clear code mode on the 24th falling edge of the next write to the device. If $\overline{CLR}$ is activated during a write sequence, the write is aborted.
6	$\overline{SYNC}$	Level-Triggered Control Input (Active Low). This is the frame synchronization signal for the input data. When $\overline{SYNC}$ goes low, it enables the input shift register, and data is transferred in on the falling edges of the following clocks. The DAC is updated following the 24th clock cycle unless $\overline{SYNC}$ is taken high before this edge, in which case the rising edge of $\overline{SYNC}$ acts as an interrupt and the write sequence is ignored by the DAC.
7	SCLK	Serial Clock Input. Data is clocked into the input shift register on the falling edge of the serial clock input. Data can be transferred at rates of up to 50 MHz.
8	DIN	Serial Data Input. This device has a 24-bit input shift register. Data is clocked into the register on the falling edge of the serial clock input.
9	V_{DD}	Power Supply Input. This device can be operated from 4.5 V to 5.5 V. Decouple the supply with a 10 µF capacitor in parallel with a 0.1 µF capacitor to GND.
10	V_{REFIN}/V_{REFOUT}	Common Reference Input/Reference Output. When the internal reference is selected, this is the reference output pin. When using an external reference, this is the reference input pin. The default for this pin is a reference input.

TYPICAL PERFORMANCE CHARACTERISTICS

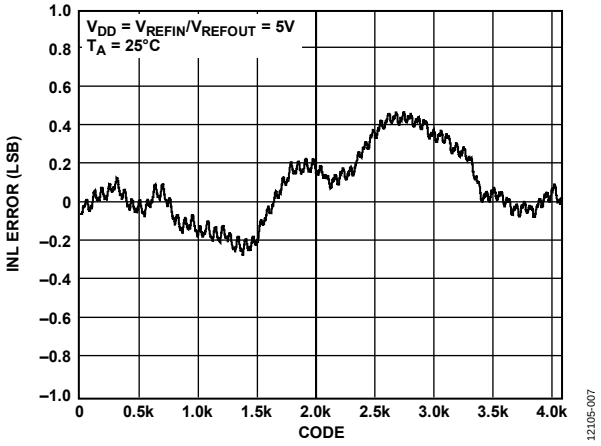

Figure 4. INL, External Reference

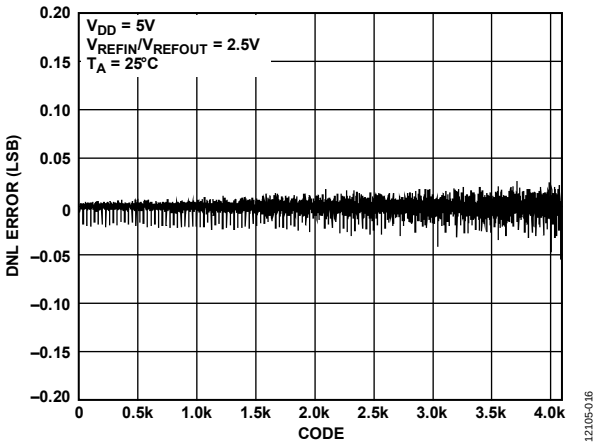

Figure 7. DNL, at 5 V V_{DD}

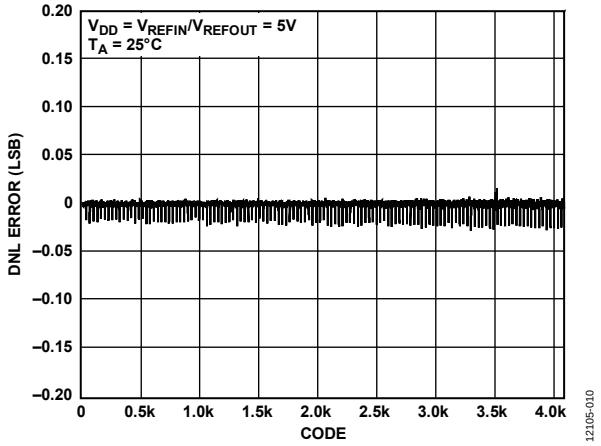

Figure 5. DNL, External Reference

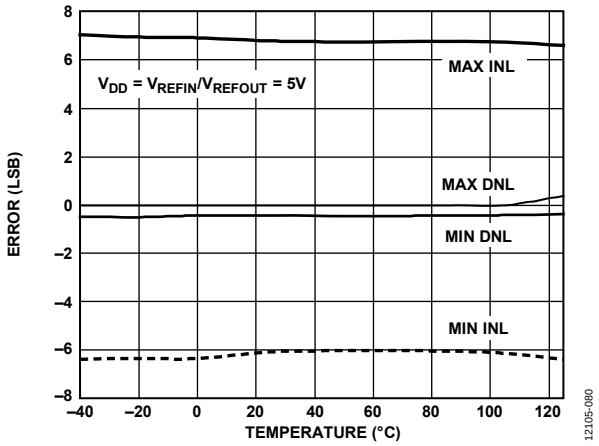

Figure 8. INL Error and DNL Error vs. Temperature

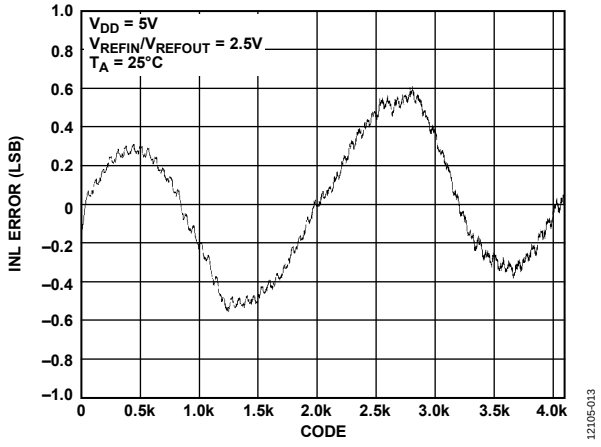

Figure 6. INL, at 5 V V_{DD}

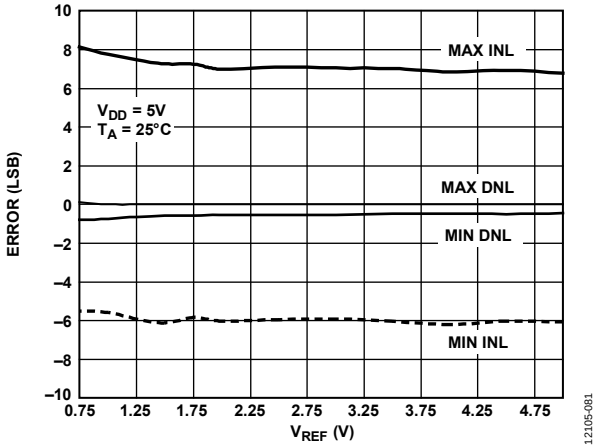

Figure 9. INL Error and DNL Error vs. V_{REF}

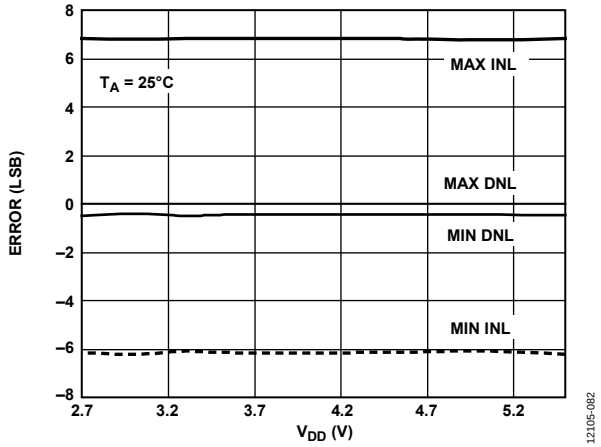

Figure 10. INL Error and DNL Error vs. V_{DD}

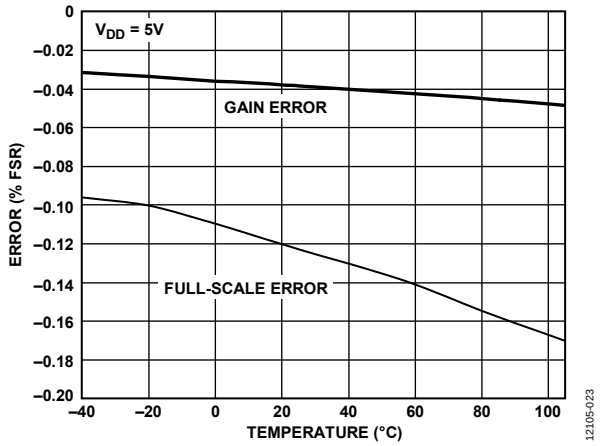

Figure 11. Gain Error and Full-Scale Error vs. Temperature

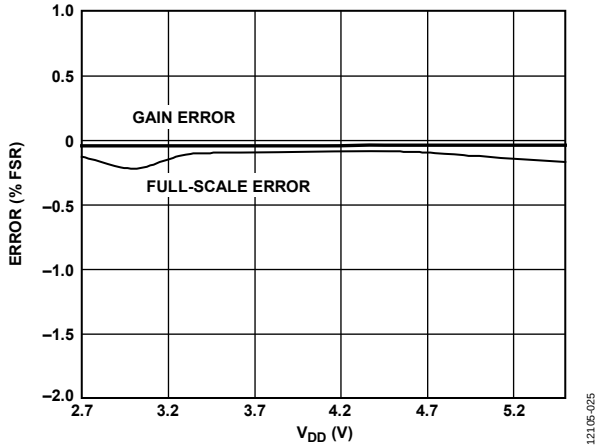

Figure 12. Gain Error and Full-Scale Error vs. V_{DD}

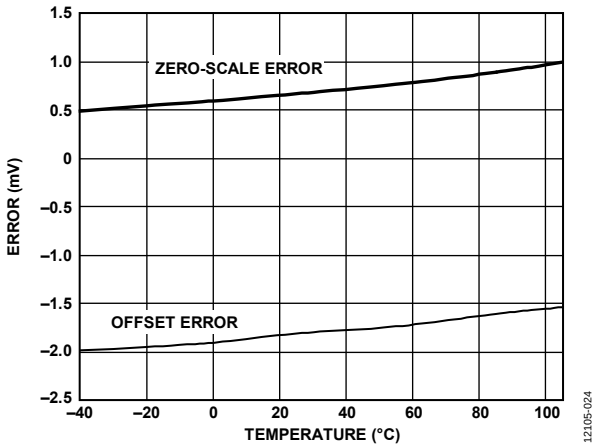

Figure 13. Zero-Scale Error and Offset Error vs. Temperature

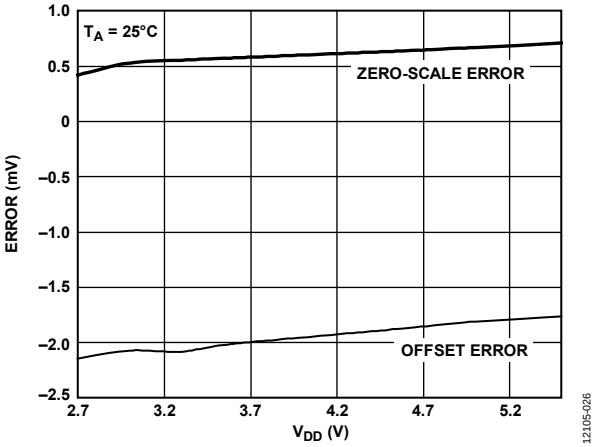

Figure 14. Zero-Scale Error and Offset Error vs. V_{DD}

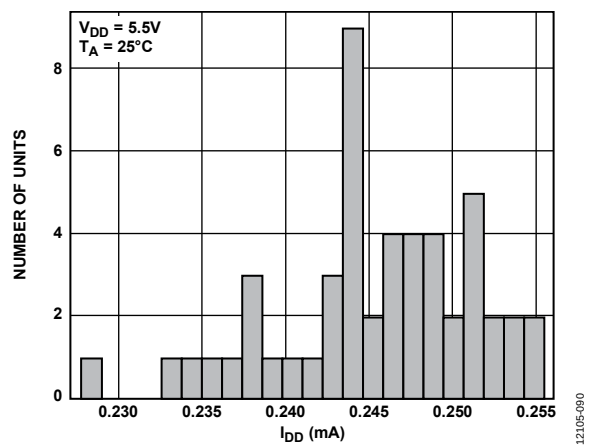

Figure 15. I_{DD} Histogram with External Reference

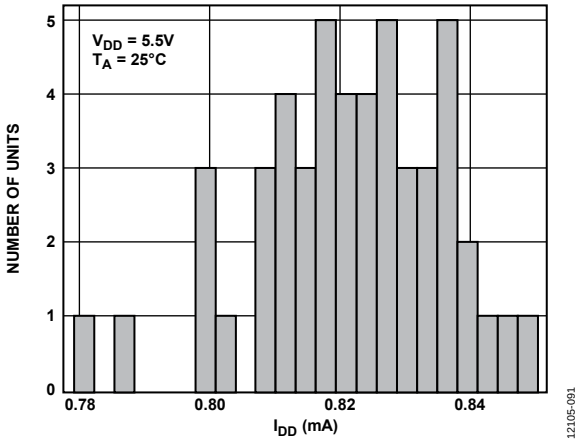

Figure 16. I_{DD} Histogram with Internal Reference

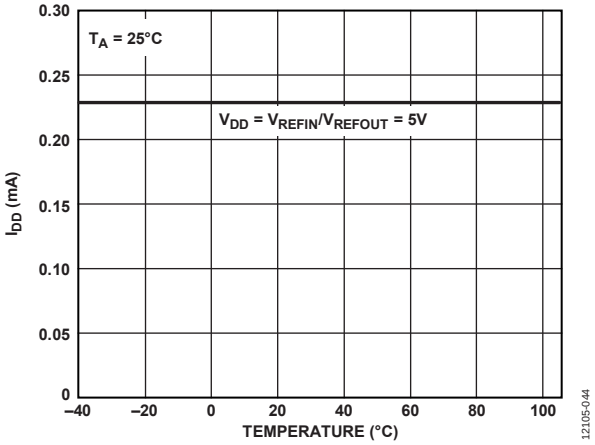

Figure 19. Supply Current vs. Temperature

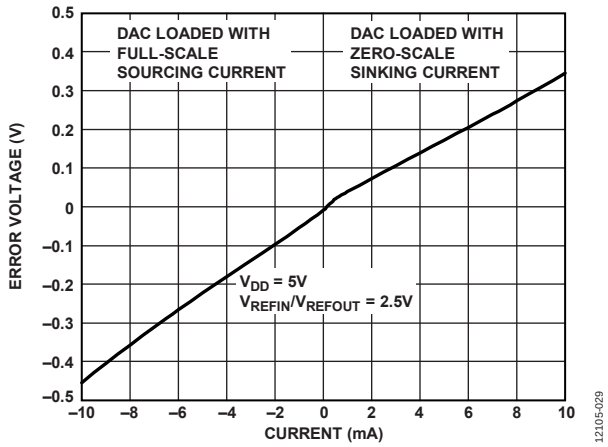

Figure 17. Headroom at Rails vs. Source and Sink Current

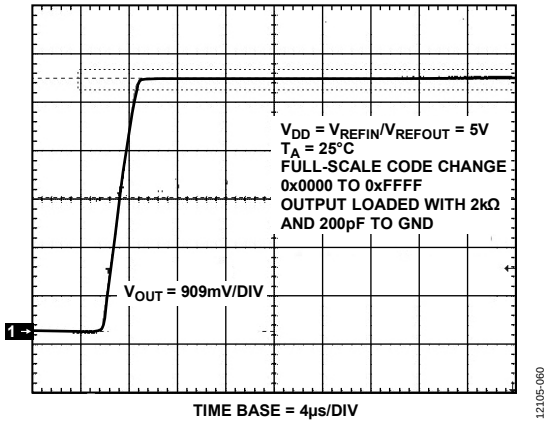

Figure 20. Full-Scale Settling Time, 5 V

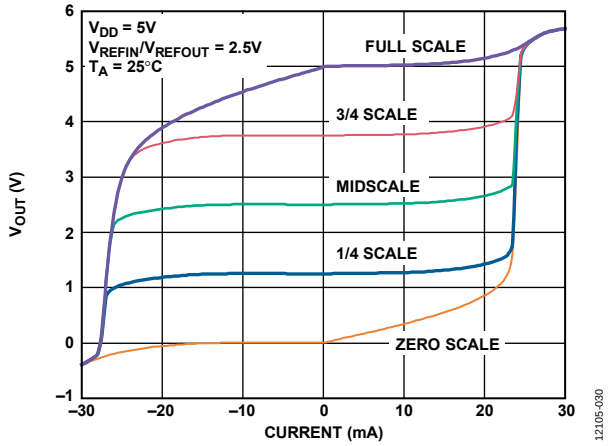

Figure 18. 5 V V_{DD} Source and Sink Capability

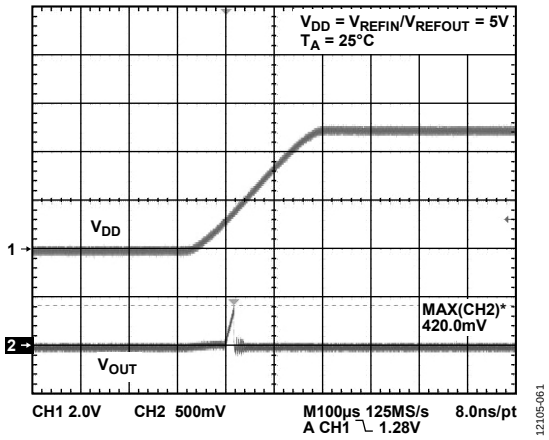

Figure 21. Power-On Reset to 0 V

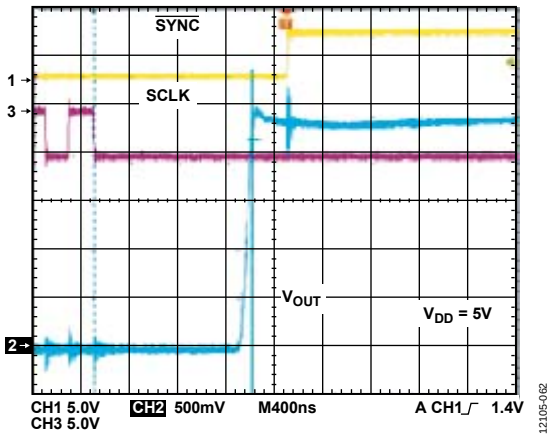

Figure 22. Exiting Power-Down to Midscale

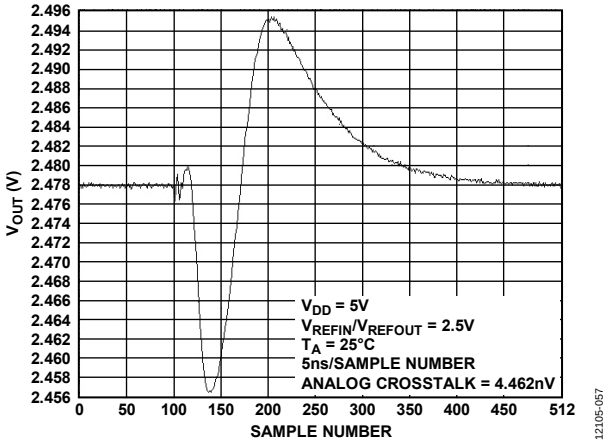

Figure 25. Analog Crosstalk, Internal Reference

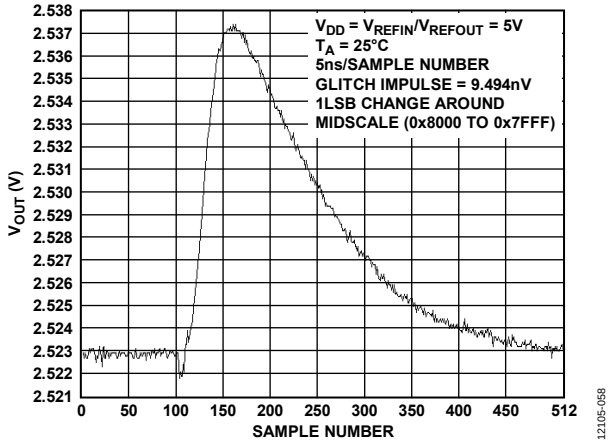

Figure 23. Digital-to-Analog Glitch Impulse (Negative)

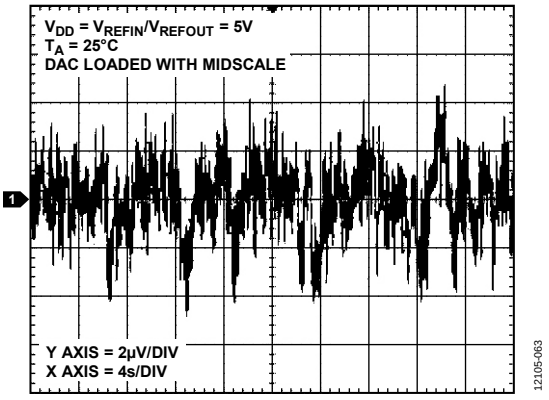

Figure 26. 0.1 Hz to 10 Hz Output Noise Plot, External Reference

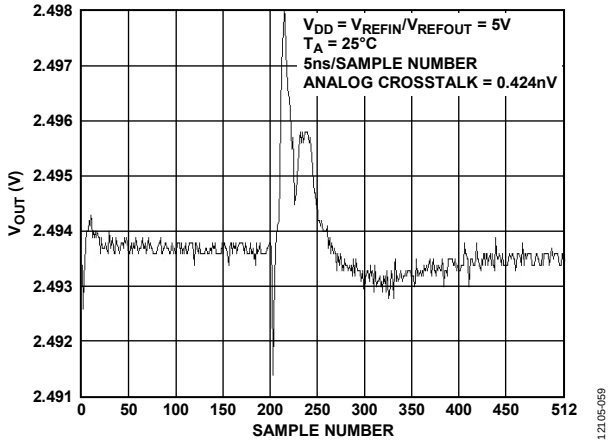

Figure 24. Analog Crosstalk, External Reference

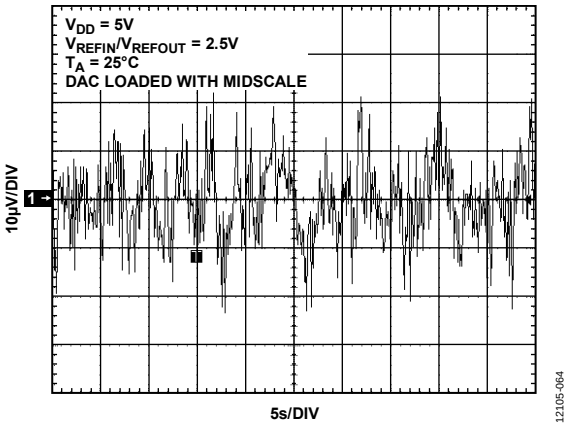

Figure 27. 0.1 Hz to 10 Hz Output Noise Plot, Internal Reference

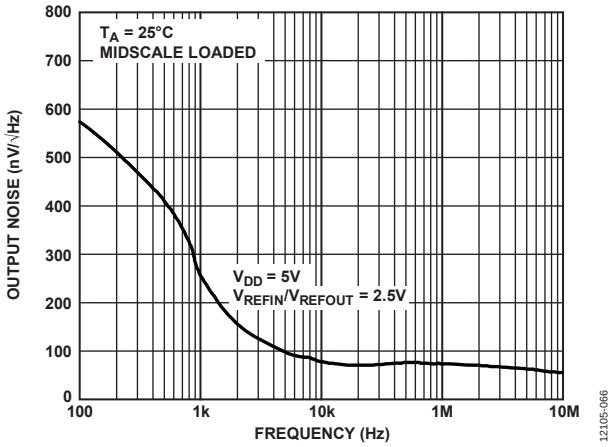

Figure 28. Noise Spectral Density, Internal Reference

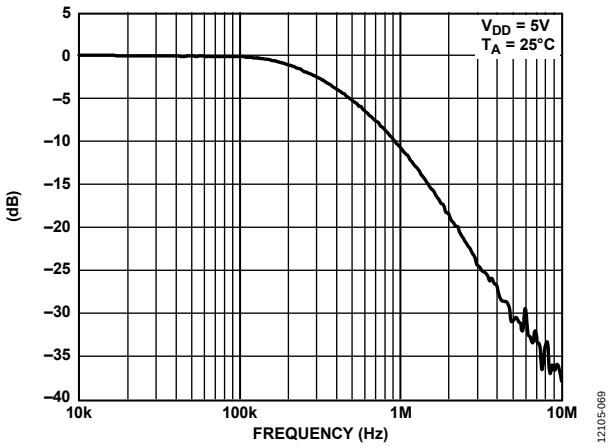

Figure 31. Multiplying Bandwidth

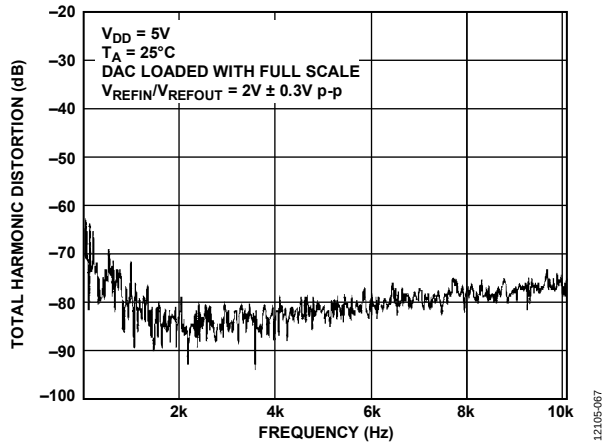

Figure 29. Total Harmonic Distortion

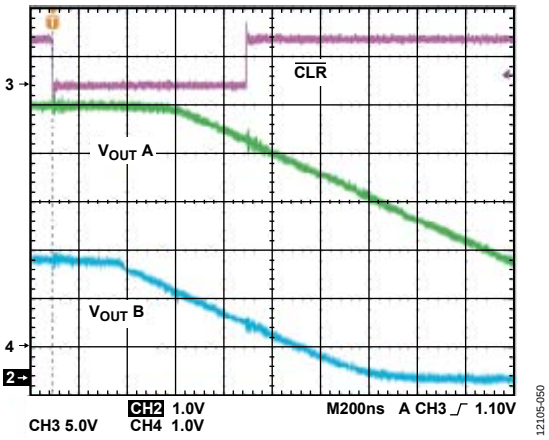

Figure 32. $\overline{CLR}$ Pulse Activation Time

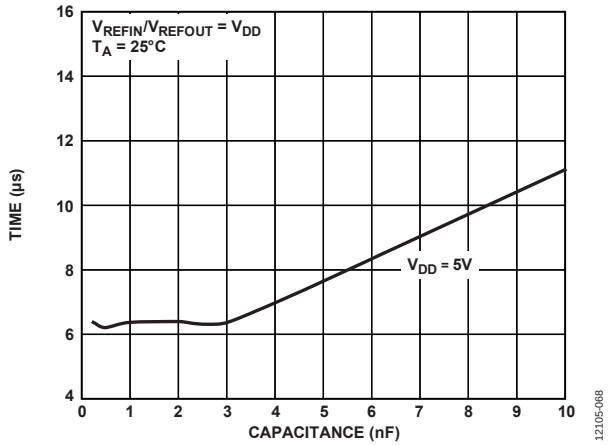

Figure 30. Settling Time vs. Capacitive Load

TERMINOLOGY

Relative Accuracy or Integral Nonlinearity (INL)
For the DAC, relative accuracy or integral nonlinearity is a measurement of the maximum deviation, in LSBs, from a straight line passing through the endpoints of the DAC transfer function. A typical INL vs. code plot is shown in Figure 4.

Differential Nonlinearity (DNL)
Differential nonlinearity (DNL) is the difference between the measured change and the ideal 1 LSB change between any two adjacent codes. A specified differential nonlinearity of ±1 LSB maximum ensures monotonicity. This DAC is guaranteed monotonic by design. A typical DNL vs. code plot is shown in Figure 5.

Zero-Scale Error
Zero-scale error is the measurement of the output error when zero code (0x0000) is loaded to the DAC register. Ideally, the output is 0 V. The zero-scale error is always positive because the output of the DAC cannot go below 0 V. It is due to a combination of the offset errors in the DAC and the output amplifier. Zero-scale error is expressed in mV. A plot of zero-scale error vs. temperature is shown in Figure 13.

Full-Scale Error
Full-scale error is the measurement of the output error when full-scale code (0xFFFF) is loaded into the DAC register. Ideally, the output is V_{DD} − 1 LSB. Full-scale error is expressed as a percentage of the full-scale range. A plot of full-scale error vs. temperature is shown in Figure 11.

Gain Error
Gain error is a measure of the span error of the DAC. It is the deviation in slope of the DAC transfer characteristic from the ideal, expressed as a percentage of the full-scale range.

Zero-Scale Error Drift
Zero-scale error drift is the measurement of the change in zero-scale error with a change in temperature. It is expressed in microvolts/°C (µV/°C).

Gain Temperature Coefficient
Gain temperature coefficient is a measurement of the change in gain error with changes in temperature. It is expressed in (ppm of full-scale range)/°C.

Offset Error
Offset error is a measure of the difference between V_{OUT} (actual) and V_{OUT} (ideal) expressed in mV in the linear region of the transfer function. Offset error is measured with Code 512 loaded in the DAC register. It can be negative or positive.

DC Power Supply Rejection Ratio (PSRR)
PSRR indicates how the output of the DAC is affected by changes in the supply voltage. PSRR is the ratio of the change in V_{OUT} to a change in V_{DD} for full-scale output of the DAC. It is measured in dB. V_{REFIN}/V_{REFOUT} is held at 2 V, and V_{DD} is varied by ±10%.

Output Voltage Settling Time
Output voltage settling time is the amount of time it takes for the output of a DAC to settle to a specified level for a ¼ to ¾ full-scale input change and is measured from the 24th falling edge of SCLK.

Digital-to-Analog Glitch Impulse
The impulse injected into the analog output when the input code in the DAC register changes state. It is normally specified as the area of the glitch in nV-sec and is measured when the digital input code is changed by 1 LSB at the major carry transition (0x7FFF to 0x8000). See Figure 23.

Digital Feedthrough
A measure of the impulse injected into the analog output of the DAC from the digital inputs of the DAC, digital feedthrough is measured when the DAC output is not updated. It is specified in nV-sec, and it is measured with a full-scale code change on the data bus, that is, from all 0s to all 1s and vice versa.

Reference Feedthrough
Reference feedthrough is the ratio of the amplitude of the signal at the DAC output to the reference input when the DAC output is not being updated (that is, $\overline{\text{LDAC}}$ is high). It is expressed in decibels (dB).

Noise Spectral Density
Noise spectral density is a measurement of the internally generated random noise, expressed in nV/√Hz. Random noise is characterized as a spectral density. It is measured by loading the DAC to midscale and measuring noise at the output. A plot of noise spectral density is shown in Figure 28.

DC Crosstalk
DC crosstalk is the dc change in the output level of one DAC in response to a change in the output of another DAC. It is measured with a full-scale output change on one DAC (or soft power-down and power-up) while monitoring another DAC kept at midscale. It is expressed in microvolts (µV).

DC crosstalk due to load current change is a measure of the impact that a change in load current on one DAC has to another DAC kept at midscale. It is expressed in microvolts/milliamps (µV/mA).

Digital Crosstalk
Digital crosstalk is the glitch impulse transferred to the output of one DAC at midscale in response to a full-scale code change (all 0s to all 1s and vice versa) in the input register of another DAC. It is measured in standalone mode and is expressed in nanovolts-second (nV-sec).

Analog Crosstalk
Analog crosstalk is the glitch impulse transferred to the output of one DAC due to a change in the output of another DAC. It is measured by loading one of the input registers with a full-scale code change (all 0s to all 1s and vice versa) while keeping LDAC high. Then pulse $\overline{\text{LDAC}}$ low and monitor the output of the DAC

whose digital code was not changed. The area of the glitch is expressed in nanovolts-second (nV-sec).

DAC-to-DAC Crosstalk
DAC-to-DAC crosstalk is the glitch impulse transferred to the output of one DAC due to a digital code change and subsequent output change of another DAC. This includes both digital and analog crosstalk. It is measured by loading one of the DACs with a full-scale code change (all 0s to all 1s and vice versa) with $\overline{\text{LDAC}}$ low and monitoring the output of another DAC. The energy of the glitch is expressed in nanovolts-second (nV-sec).

Multiplying Bandwidth
The amplifiers within the DAC have a finite bandwidth. The multiplying bandwidth is a measure of this finite bandwidth. A sine wave on the reference (with full-scale code loaded to the DAC) appears on the output. The multiplying bandwidth is the frequency at which the output amplitude falls to 3 dB below the input.

Total Harmonic Distortion (THD)
Total harmonic distortion is the difference between an ideal sine wave and its attenuated version using the DAC. The sine wave is used as the reference for the DAC, and THD is a measurement of the harmonics present on the DAC output. It is measured in decibels (dB).

THEORY OF OPERATION

DIGITAL-TO-ANALOG ARCHITECTURE

The AD5623R-EP DAC is fabricated on a CMOS process. The architecture consists of a string DAC followed by an output buffer amplifier. Figure 33 shows a block diagram of the DAC architecture.

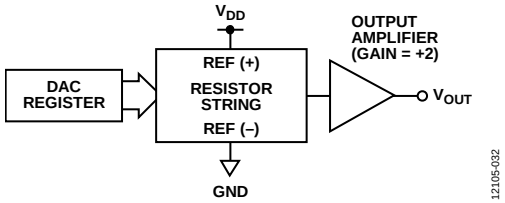

Figure 33. DAC Architecture

Because the input coding to the DAC is straight binary, the ideal output voltage when using an external reference is given by

$$V_{OUT} = V_{REFIN} \times \left(\frac{D}{2^N}\right)$$

The ideal output voltage when using the internal reference is given by

$$V_{OUT} = 2 \times V_{REFOUT} \times \left(\frac{D}{2^N}\right)$$

where:
D is the decimal equivalent of the binary code that is loaded to the DAC register, 0 to 4095 for the AD5623R-EP (12-bit).
N is the DAC resolution.

RESISTOR STRING

The resistor string section is shown in Figure 34. It is simply a string of resistors, each of Value R. The code loaded to the DAC register determines at which node on the string the voltage is tapped off to be fed into the output amplifier. The voltage is tapped off by closing one of the switches connecting the string to the amplifier. Because it is a string of resistors, it is guaranteed monotonic.

OUTPUT AMPLIFIER

The output buffer amplifier can generate rail-to-rail voltages on its output, which gives an output range of 0 V to V_{DD}. It can drive a load of 2 kΩ in parallel with 1000 pF to GND. The source and sink capabilities of the output amplifier is shown in Figure 17. The slew rate is 1.8 V/µs with a ¼ to ¾ full-scale settling time of 3 µs.

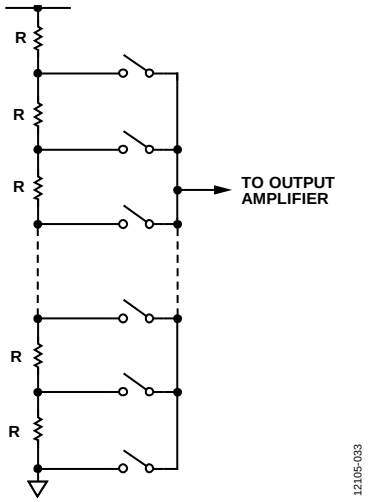

Figure 34. Resistor String

INTERNAL REFERENCE

The AD5623R-EP on-chip reference is off at power-up and is enabled via a write to the input shift register. See the Internal Reference Setup section for details.

The AD5623R-EP has a 2.5 V, ±10 ppm/°C reference giving a full-scale output of 5 V. The internal reference is available at the V_{REFIN}/V_{REFOUT} pin. A buffer is required if the reference output is used to drive external loads. When using the internal reference, it is recommended that a 100 nF capacitor be placed between the reference output and GND for reference stability.

EXTERNAL REFERENCE

The V_{REFIN}/V_{REFOUT} pin on the AD5623R-EP allows the use of an external reference if the application requires it. The on-chip reference is off at power-up, the default condition. The AD5623R-EP can be operated from a single 4.5 V to 5.5 V supply.

SERIAL INTERFACE

The AD5623R-EP has a 3-wire serial interface ($\overline{\text{SYNC}}$, SCLK, and DIN) that is compatible with SPI, QSPI, and MICROWIRE interface standards, as well as with most DSPs. See Figure 2 for a timing diagram of a typical write sequence.

The write sequence begins by bringing the $\overline{\text{SYNC}}$ line low. Data from the DIN line is clocked into the 24-bit input shift register on the falling edge of SCLK. The serial clock frequency can be as high as 50 MHz, making the AD5623R-EP compatible with high speed DSPs. On the 24th falling clock edge, the last data bit is clocked in and the programmed function is executed, for example, a change in DAC register contents and/or a change in the mode of operation.

At this stage, the $\overline{\text{SYNC}}$ line can be kept low or be brought high. In either case, it must be brought high for a minimum of 15 ns before the next write sequence, so that a falling edge of $\overline{\text{SYNC}}$ can initiate the next write sequence.

Because the $\overline{SYNC}$ buffer draws more current when V_{IN} = 2 V than it does when V_{IN} = 0.8 V, idle $\overline{SYNC}$ low between write sequences for even lower power operation. As mentioned previously, it must, however, be brought high again just before the next write sequence.

INPUT SHIFT REGISTER

The input shift register is 24 bits wide (see Figure 35). The first two bits are don't cares. The next three are Command Bit C2 to Command Bit C0 (see Table 7), followed by the 3-bit DAC Address A2 to DAC Address A0 (see Table 8), and, finally, the 12-bit data-word.

The data-word comprises the 12-bit input codes, followed by four don't care bits. The data bits are transferred to the DAC register on the 24th falling edge of SCLK.

Table 7. Command Definition

C2	C1	C0	Command
0	0	0	Write to Input Register n
0	0	1	Update DAC Register n
0	1	0	Write to Input Register n, update all (software $\overline{LDAC}$)
0	1	1	Write to and update DAC Channel n
1	0	0	Power down/power up DAC
1	0	1	Software reset
1	1	0	$\overline{LDAC}$ setup
1	1	1	Internal reference setup (on/off)

Table 8. Address Command

A2	A1	A0	Address (n)
0	0	0	DAC A
0	0	1	DAC B
0	1	0	Reserved
0	1	1	Reserved
1	1	1	All DACs

$\overline{SYNC}$ INTERRUPT

In a normal write sequence, the $\overline{SYNC}$ line is kept low for at least 24 falling edges of SCLK, and the DAC is updated on the 24th falling edge. However, if $\overline{SYNC}$ is brought high before the 24th falling edge, this acts as an interrupt to the write sequence. The shift register is reset, and the write sequence is seen as invalid. Neither an update of the DAC register contents nor a change in the operating mode occurs (see Figure 36).

POWER-ON RESET

The AD5623R-EP contains a power-on reset circuit that controls the output voltage during power-up. The output of the DACs power up to 0 V, and the output remains there until a valid write sequence is made to the DACs. This is useful in applications where it is important to know the state of the output of the DACs while they are in the process of powering up. Any events on $\overline{LDAC}$ or $\overline{CLR}$ during power-on reset are ignored.

SOFTWARE RESET

The AD5623R-EP contain a software reset function. Command 101 is reserved for the software reset function (see Table 7). The software reset command contains two reset modes that are software-programmable by setting bit DB0 in the input shift register. Table 9 shows how the state of the bit corresponds to the mode of operation of the device. Table 11 shows the contents of the input shift register during the software reset mode of operation.

Table 9. Software Reset Modes

DB0	Registers Reset to Zero
0	DAC register Input register
1 (Power-On Reset)	DAC register Input register $\overline{LDAC}$ register Power-down register Internal reference setup register

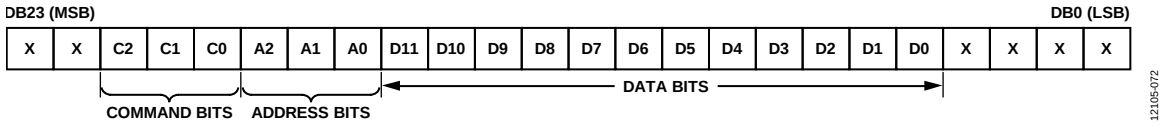

Figure 35. Input Shift Register Contents

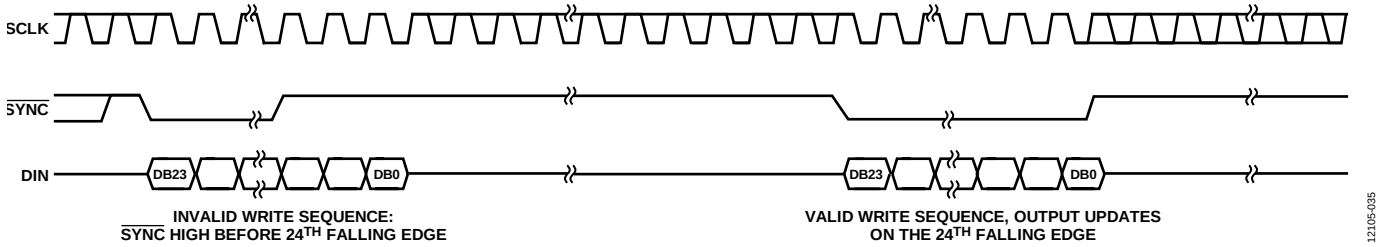

Figure 36. $\overline{SYNC}$ Interrupt Facility

POWER-DOWN MODES

The AD5623R-EP contains four separate modes of operation: normal operation and three power-down modes. Use Command 100 for the power-down function (see Table 7). These modes are software-programmable by setting Bit DB5 and Bit DB4 in the input shift register. Table 10 shows how the state of the bits corresponds to the mode of operation of the device. Any or all DACs (DAC B and DAC A) can be powered down to the selected mode by setting the corresponding two bits (Bit DB1 and Bit DB0) to 11.

By executing the same Command 100, any combination of DACs can be powered up by setting Bit DB5 and Bit DB4 to normal operation mode.

To select the combination of DAC channels to power up, set the corresponding bits (DB1 and DB0) to 11. See Table 12 for contents of the input shift register during power-down/power-up operation.

The DAC output powers up to the value in the input register while $\overline{\text{LDAC}}$ is low. If $\overline{\text{LDAC}}$ is high, the DAC output powers up to the value held in the DAC register before power-down.

Table 10. Modes of Operation

DB5	DB4	Operating Mode
0	0	Normal operation
0	1	Power-down mode: 1 kΩ to GND
1	0	Power-down mode: 100 kΩ to GND
1	1	Power-down mode: three-state

When both Bit DB5 and Bit DB4 are set to 0, the device works normally, with its normal power consumption of 0.25 mA at 5 V. However, for the three power-down modes, the supply current falls to 0.48 µA at 5 V. Not only does the supply current fall, but the output stage is also internally switched from the output of the amplifier to a resistor network of known values. This has the advantage that the output impedance of the device is known while it is in power-down mode. The outputs can either be connected internally to GND through a 1 kΩ or 100 kΩ resistor or left open-circuited (three-state) (see Figure 37).

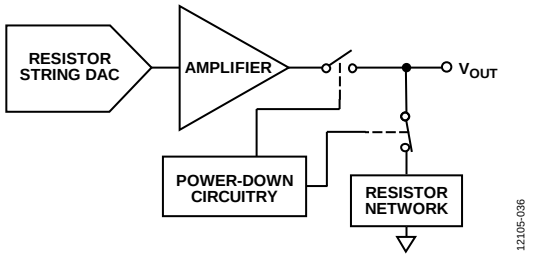

Figure 37. Output Stage During Power-Down

The bias generator, the output amplifier, the resistor string, and other associated linear circuitry are shut down when power-down mode is activated. However, the contents of the DAC register are unaffected when in power-down. The time to exit power-down is typically 4 µs for V_{DD} = 5 V (see Figure 22).

Table 11. 24-Bit Input Shift Register Contents for Software Reset Command

MSB **LSB**

DB23 to DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15 to DB1	DB0
X	1	0	1	X	X	X	X	1/0
Don't care	Command bits (C2 to C0)			Address bits (A2 to A0), don't care			Don't care	Determines software reset mode

Table 12. 24-Bit Input Shift Register Contents of Power-Down/Power-Up Function

MSB **LSB**

DB23 to DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15 to DB6	DB5	DB4	DB3	DB2	DB1	DB0
X	1	0	0	X	X	X	X	PD1	PD0	X	X	DAC B	DAC A
Don't care	Command bits (C2 to C0)			Address bits (A2 to A0), don't care			Don't care	Power-down mode		Don't care		Power-down/power-up channel selection; set bits to 11 to select channel	

Table 13. 24-Bit Input Shift Register Contents for $\overline{\text{LDAC}}$ Setup Command

MSB **LSB**

DB23 to DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15 to DB2	DB1	DB0
X	1	1	0	X	X	X	X	$\overline{\text{LDAC}}$	
Don't care	Command bits (C2 to C0)			Address bits (A3 to A0), don't care			Don't care	Set bits according to Table 14 for required mode of operation	

$\overline{\text{LDAC}}$ FUNCTION

The AD5623R-EP DAC has a double-buffered interface consisting of two banks of registers: input registers and DAC registers. The input registers are connected directly to the input shift register, and the digital code is transferred to the relevant input register on completion of a valid write sequence. The DAC registers contain the digital code used by the resistor strings.

Access to the DAC registers is controlled by the $\overline{\text{LDAC}}$ pin. When the $\overline{\text{LDAC}}$ pin is high, the DAC registers are latched and the input registers can change state without affecting the contents of the DAC registers. When $\overline{\text{LDAC}}$ is brought low, however, the DAC registers become transparent and the contents of the input registers are transferred to them. The double-buffered interface is useful if the user requires simultaneous updating of all DAC outputs. The user can write to one of the input registers individually and then, by bringing $\overline{\text{LDAC}}$ low when writing to the other DAC input register, all outputs update simultaneously.

The device contains an extra feature whereby a DAC register is not updated unless its input register has been updated since the last time $\overline{\text{LDAC}}$ was brought low. Normally, when $\overline{\text{LDAC}}$ is brought low, the DAC registers are filled with the contents of the input registers. The DAC register updates only if the input register has changed since the last time the DAC register was updated, thereby removing unnecessary digital crosstalk.

The outputs of all DACs can be simultaneously updated, using the hardware $\overline{\text{LDAC}}$ pin.

Synchronous $\overline{\text{LDAC}}$

The DAC registers are updated after new data is read in on the falling edge of the 24th SCLK pulse. $\overline{\text{LDAC}}$ can be permanently low or pulsed, as shown in Figure 2.

Asynchronous $\overline{\text{LDAC}}$

The outputs are not updated at the same time that the input registers are written to. When $\overline{\text{LDAC}}$ goes low, the DAC registers are updated with the contents of the input register.

The $\overline{\text{LDAC}}$ register gives the user full flexibility and control over the hardware $\overline{\text{LDAC}}$ pin. This register allows the user to select the combination of channels to simultaneously update when the hardware $\overline{\text{LDAC}}$ pin is executed. Setting the $\overline{\text{LDAC}}$ bits to 00 for a DAC channel means that the update of this channel is controlled by the $\overline{\text{LDAC}}$ pin. If these bits are set to 11, this channel synchronously updates; that is, the DAC register is updated after new data is read in, regardless of the state of the $\overline{\text{LDAC}}$ pin. It effectively sees the $\overline{\text{LDAC}}$ pin as being pulled low. See Table 14 for the $\overline{\text{LDAC}}$ mode of operation. This flexibility is useful in applications where the user wants to simultaneously update select channels while the rest of the channels are synchronously updating.

Writing to the DAC using Command 110 loads the $\overline{\text{LDAC}}$ bits, [DB1:DB0]. The default for each channel is 00; that is, the $\overline{\text{LDAC}}$ pin works normally. Setting the bits to 11 means the DAC register is updated, regardless of the state of the $\overline{\text{LDAC}}$ pin. See Table 13 for contents of the input shift register during the $\overline{\text{LDAC}}$ register setup command.

Table 14. $\overline{\text{LDAC}}$ Mode of Operation

$\overline{\text{LDAC}}$ Bits (DB1 to DB0)	$\overline{\text{LDAC}}$ Pin	$\overline{\text{LDAC}}$ Operation
00	1/0	Determined by $\overline{\text{LDAC}}$ pin for both DAC A and DAC B.
01	1/0	$\overline{\text{LDAC}}$ controls DAC A only
10	1/0	$\overline{\text{LDAC}}$ controls DAC B only
11	X = don't care	The DAC registers are updated after new data is read in on the falling edge of the 24th SCLK pulse.

INTERNAL REFERENCE SETUP

The on-chip reference is off at power-up by default. This reference can be turned on or off by setting a software programmable bit, DB0, in the input shift register. Table 15 shows how the state of the bit corresponds to the mode of operation. Command 111 is reserved for setting up the internal reference (see Table 7). See Table 16 for the contents of the input shift register during the internal reference setup command.

Table 15. Reference Setup

Internal Reference Setup (DB0)	Action
0	Reference off (default)
1	Reference on

Table 16. 32-Bit Input Shift Register Contents for Internal Reference Setup Function

MSB **LSB**

DB23 to DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15 to DB1	DB0
X	1	1	1	X	X	X	X	1/0
Don't care	Command bits (C2 to C0)			Address bits (A2 to A0), don't care			Don't care	Internal reference setup

MICROPROCESSOR INTERFACING

AD5623R-EP to Blackfin® ADSP-BF53x Interface

Figure 38 shows a serial interface between the AD5623R-EP and the Blackfin ADSP-BF53x microprocessor. The ADSP-BF53x processor family incorporates two dual-channel synchronous serial ports, SPORT1 and SPORT0, for serial and multiprocessor communications. Using SPORT0 to connect to the AD5623R-EP, the setup for the interface is as follows: DT0PRI drives the DIN pin of the AD5623R-EP, while TSCLK0 drives the SCLK pin of the device. The $\overline{\text{SYNC}}$ pin is driven from TFS0.

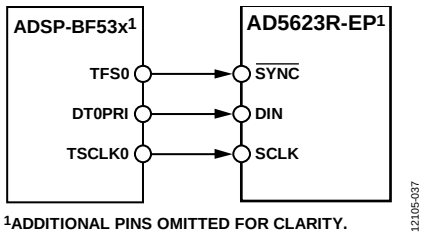

Figure 38. AD5623R-EP to Blackfin ADSP-BF53x Interface

AD5623R-EP to M68HC11/MC68L11 Interface

Figure 39 shows a serial interface between the AD5623R-EP and the M68HC11/MC68L11 microcontroller. SCK of the M68HC11/MC68L11 drives the SCLK of the AD5623R-EP, and the MOSI output drives the serial data line of the DAC.

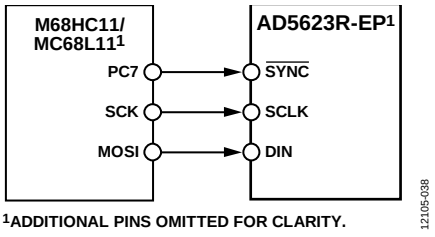

Figure 39. AD5623R-EP to M68HC11/MC68L11 Interface

The $\overline{\text{SYNC}}$ signal is derived from a port line (PC7). The setup conditions for correct operation of this interface are as follows: the M68HC11/MC68L11 microcontroller is configured with its CPOL bit as 0, and its CPHA bit as 1. When data is being transmitted to the DAC, the $\overline{\text{SYNC}}$ line is taken low (PC7). When the M68HC11/MC68L11 microcontroller is configured as described previously, data appearing on the MOSI output is valid on the falling edge of SCK. Serial data from the M68HC11/MC68L11 is transmitted in 8-bit bytes with only eight falling clock edges occurring in the transmit cycle.

Data is transmitted MSB first. To load data to the AD5623R-EP, PC7 is left low after the first eight bits are transferred, and a second serial write operation is performed to the DAC. PC7 is taken high at the end of this procedure.

AD5623R-EP to 80C51 Interface

Figure 40 shows a serial interface between the AD5623R-EP and the 80C51 microcontroller. The setup for the interface is as follows: TxD of the 80C51 drives SCLK of the AD5623R-EP, and RxD drives the serial data line of the device. The $\overline{\text{SYNC}}$ signal is again derived from a bit-programmable pin on the port. In this case, Port Line P3.3 is used. When data is to be transmitted to the AD5623R-EP, P3.3 is taken low. The 80C51 transmits data in 8-bit bytes only; thus, only eight falling clock edges occur in the transmit cycle. To load data to the DAC, P3.3 is left low after the first eight bits are transmitted, and a second write cycle is initiated to transmit the second byte of data. P3.3 is taken high following the completion of this cycle.

The 80C51 outputs the serial data LSB first. Take into account that the AD5623R-EP must receive data with the MSB first when transmitting from the 80C51.

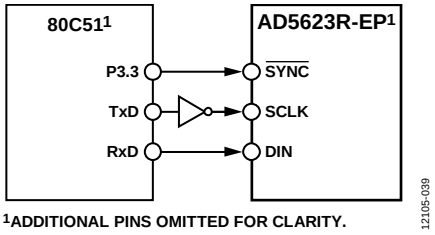

Figure 40. AD5623R-EP to 80C51 Interface

AD5623R-EP to MICROWIRE Interface

Figure 41 shows an interface between the AD5623R-EP and any MICROWIRE-compatible device. Serial data is shifted out on the falling edge of the serial clock and is clocked into the AD5623R-EP on the rising edge of the SK.

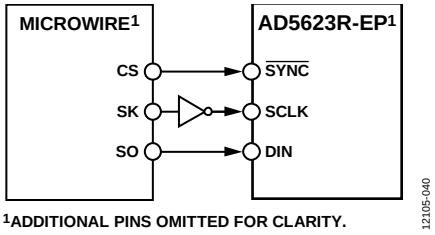

Figure 41. AD5623R-EP to MICROWIRE Interface

APPLICATIONS INFORMATION

USING A REFERENCE AS A POWER SUPPLY

Because the supply current required by the AD5623R-EP is extremely low, an alternative option is to use a voltage reference to supply the required voltage to the device (see Figure 42). This is especially useful if the power supply is quite noisy or if the system supply voltages are at some value other than 5 V or 3 V, for example, 15 V. The voltage reference outputs a steady supply voltage for the AD5623R-EP. If the low dropout REF195 is used, it must supply 500 µA of current to the AD5623R-EP, with no load on the output of the DAC. When the DAC output is loaded, the REF195 also needs to supply the current to the load. The total current required (with a 5 kΩ load on the DAC output) is

500 µA + (5 V/5 kΩ) = 1.25 mA

The load regulation of the REF195 is typically 2 ppm/mA, which results in a 3 ppm (15 µV) error for the 1.5 mA current drawn from it. This corresponds to a 0.196 LSB error.

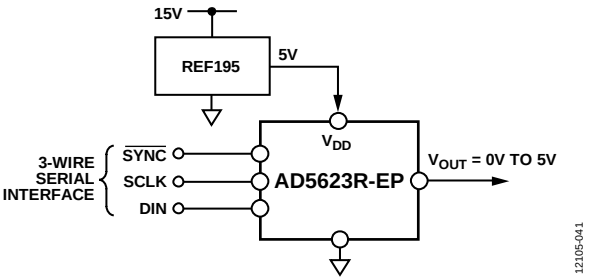

Figure 42. REF195 as Power Supply to the AD5623R-EP

POWER SUPPLY BYPASSING AND GROUNDING

When accuracy is important in a circuit, it is helpful to carefully consider the power supply and ground return layout on the board. For the printed circuit board containing the AD5623R-EP, use separate analog and digital sections, each having its own area of the board.

If the AD5623R-EP is in a system where other devices require an AGND to DGND connection, make the connection at one point only. Ensure that this ground point is as close as possible to the AD5623R-EP.

Bypass the power supply to the AD5623R-EP with 10 µF and 0.1 µF capacitors. Place the capacitors as close as possible to the device, with the 0.1 µF capacitor ideally right up against the device. The 10 µF capacitors are the tantalum bead type. It is important that the 0.1 µF capacitor have low effective series resistance (ESR) and effective series inductance (ESI), which is found, for example, in common ceramic types of capacitors.

This 0.1 µF capacitor provides a low impedance path to ground for high frequencies caused by transient currents due to internal logic switching.

Ensure that the power supply line itself has as large a trace as possible to provide a low impedance path and to reduce glitch effects on the supply line. Shield clocks and other fast switching digital signals from other parts of the board by digital ground. Avoid crossover of digital and analog signals, if possible. When traces cross on opposite sides of the board, ensure that they run at right angles to each other to reduce feedthrough effects through the board. The best board layout technique is the microstrip technique, where the component side of the board is dedicated to the ground plane only and the signal traces are placed on the solder side. However, this is not always possible with a 2-layer board.

OUTLINE DIMENSIONS

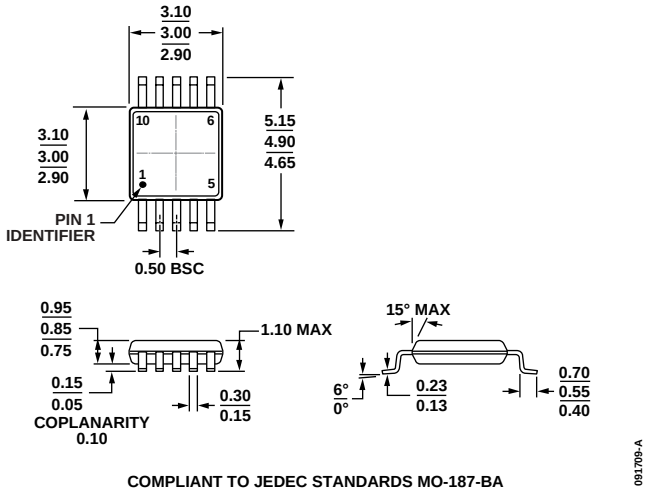

Figure 43. 10-Lead Mini Small Outline Package [MSOP]
(RM-10)
Dimensions shown in millimeters

ORDERING GUIDE

Model[1]	Temperature Range	Accuracy	Internal Reference	Package Description	Package Option	Branding
AD5623RSRMZ-EP-5R7	−55°C to +105°C	±1.5 LSB INL	2.5 V	10-Lead MSOP	RM-10	DN9

[1] Z = RoHS Compliant Part.

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